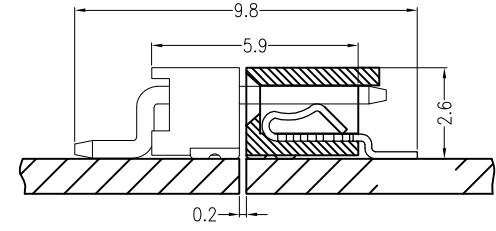
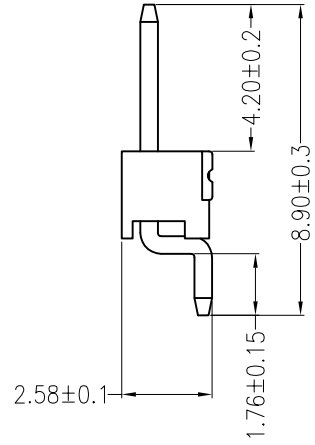
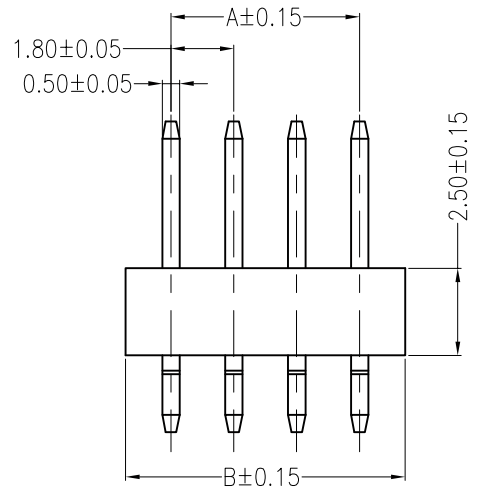
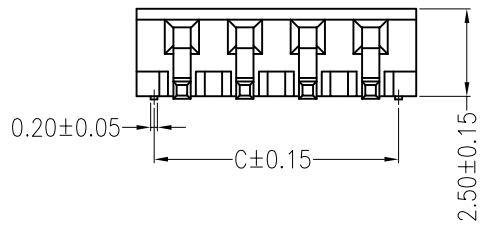


REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2016.05.06



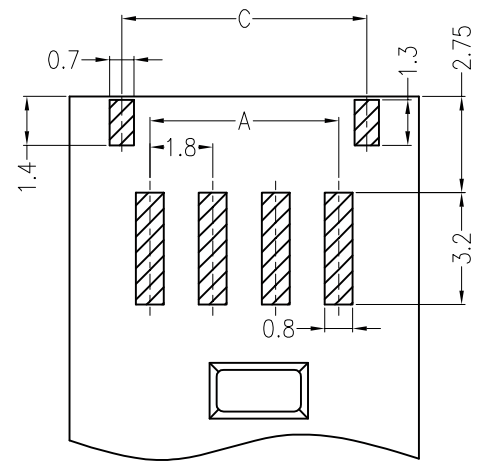
Assembly Layout



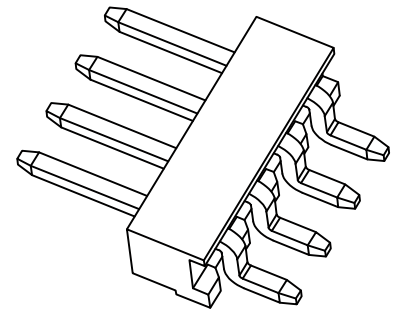
	DIM.A	DIM.B	DIM.C
01		B = 2.60	C = 1.60
02	A = 1.80	B = 4.40	C = 3.40
03	A = 3.60	B = 6.20	C = 5.20
04	A = 5.40	B = 8.00	C = 7.00
03(2)	A = 3.60	B = 6.20	C = 5.20
04(2)	A = 5.40	B = 8.00	C = 7.00
04(3)	A = 5.40	B = 8.00	C = 7.00

主要技术参数 Main Specifications

- 接触电阻 (Contact resistance): $\leq 20m\Omega$
- 绝缘电阻 (Insulation resistance): $\geq 800M\Omega$
- 额定电压 (Rated voltage): 125V AC DC
- 额定电流 (Rated current): 1.0A AC DC
- 耐电压 (Withstand Voltage): 800V AC/minute
- 温度范围 (Temperature Range): $-25^{\circ}C \sim +105^{\circ}C$



Mating Aluminum plate detail



ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C	SOLDER TAB	2 PCS	PhosphorBronze	MATTE Sn-plated
B	CONTACT	01~04PCS	Brass	MATTE Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE

LEDsconn			TITLE: -	
			1.8mmPITCH 90°WAFER SMT TYPE	
X.±0.5	X.±5°	USE: CUSTOMER	PART NO.:	
.X±0.3	.X±2°			
.XX±0.25	.XX±1°	APPD: 邵敬和	DWG NO.:	
--	--	CHKD: 田峰		
UNITS: mm		DR: 吴丹平	SCALE 1 : 1	SHEET 1 / 1